CHEMICAL CLEAN/ETCH

MODEL CESx133AR

DESCRIPTION: MODEL CESx133AR

The ***highly efficient*** Model CESx133AR is the ideal for Cleaning and Etching Wafers, Photomask, and Substrates. The ***very reliable*** and ***cost effective*** system utilizes proven assortment of technologies on individual or multiple media. The CESx133AR can be configured with several process dispense options from Brush for Sulfuric Peroxide, Surfactant, and/or DI-H_2O as well as for Surface Agitation to Expedite Reactions; Megasonic Nozzles for DI-H_2O or Chemistries; Low pressure nozzles for chemistry dispenses; Heaters for chemistries and DI-H_2O; Nitrogen Assist and much more. The Rapid and Effective Drying technique combines Variable Spin Speeds; optional Heated DI-H_2O; and Nitrogen Assist. The System is very safe, having "Rinse to pH" before access to the substrate to minimize exposure to chemistries. The System is designed to be **Automation Ready (AR)**

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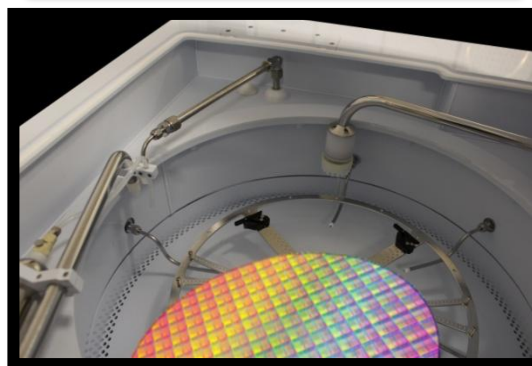

TYPICAL CLEANING CHAMBER & CHUCK

FEATURES: CONTROL & SAFETY

- System Designed for Significant Control & Safety
- Up to Twenty One (21) Inches on Diagonal/Diameter or Multiples of Smaller Size Substrates.
- Main Spindle Assembly having DC Brushless Servo Motor for precise speed control & indexing.
- Adjustable Arm Speed and Travel Positions with Arms of Teflon Coated Stainless Steel.
- Radially Exhausted Chamber for Maximum Laminar Flow with N_2 feed at Top of the lid.
- DI-H_2O Heater for Clean & Dry Assist.
- Process containment wetted surfaces of chemically compatible material either PVDF or optional PTFE.
- Stand-alone Polypropylene Cabinet or optional (shown) Stainless Steel Frame & Skins.
- Microprocessor Control Capable of Retaining Thirty (30) Recipes having thirty (30) Steps each in Memory. Both number of Recipes & Steps are expandable upon request.
- Built in Safety Interlocks & Double Containment.
- Rinse to pH of entire process area & substrate with interlocks to prohibit access to process area & control Drain and Spindle Speed till safe.
- Push Button Lid Open/Close.
- Touch Screen Graphic User Interface (GUI) with Ease of Programming & Security Lockouts with On-Screen Error Reporting.
- Drain Diverter Valves for Chemical & House Drains

OPTIONS: UP TO FOUR OSCILLATING DISPENSE ARMS

- Various sizes & types of chucks for Wafers, Photomask, and other Substrates.
- Auto Up/Down Oscillating Adjustable Self Cleaning Brush Assembly for chemical, Surfactant, & DI-H_2O Dispenses.
- Oscillating Megasonic Nozzles & Megpies for DI-H_2O or Chemical Dispense Arm.
- Fixed or Oscillating Low Pressure Dispense with various Nozzles for DI-H_2O &/or Chemistries.
- Chemical Cabinet with weight Scale Dispense Canisters, Digital Flow Meter & Pump.
- Heater for Chemical & DI-H_2O Dispenses.
- Secondary Containment With Leak Detection
- Point of Use Mixing Systems.
- FM4910 Fire Retardant Cabinet & Process Area Materials
- Designed to SEMI S2/S8 guidelines.

ULTRA *t* Equipment Company, Inc.
41980 Christy Street, Fremont, CA 94538
TEL: (510) 440-3900 FAX: (510) 440-3920
URL: www.ultrat.com